The IEEE Communications Society invites the world’s leading researchers and engineers from academia, industry and government to exchange their ideas at the IEEE ICC 2009 conference in Dresden, Germany in June 2009. It will be hosted at the International Congress Center of Dresden which lies in the heart of the historical city amongst its popular sights: the Semper Opera House, the Zwinger and the Frauenkirche.

Besides the opportunity for high-quality discussions about the most recent technologies and business applications, the IEEE ICC 2009 offers an extraordinary visibility with the powerful, international audience at the conference. The IEEE ICC attracts the “Who’s Who” in communications, i.e., leading customers, operators, vendors, researchers, investors and press. It has a long track record and an increasingly powerful, loyal audience and is considered since 1965 as a “major communications event”. The character of the event as a place where important ideas are exchanged, recent developments are discussed and current products are presented is evident and continually reinforced throughout the event.

To improve the conference’s diversity, the ICC 2009 provides an integrated exhibition area close to technical sessions, coffee areas and poster areas to ensure frequent attendance. This is an excellent chance to present your company and its recent results, as well as to get in touch with the best and most ambitious talents in industry and academia. In addition, to provide you the best possible benefit, the exhibition areas will be grouped by topic.

The following exhibition booth dimensions are offered:
- 2 m x 3 m for € 2,500
- 2 m x 6 m for € 5,000
- 2 m x 9 m for € 7,500
- 2 m x 12 m for € 10,000

Each booth is equipped with a power supply. All requests such as furniture and other additional equipment can be individually arranged with the conference organizer and may be subject to additional fees.

Call for Exhibitions

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